

TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	Solder Film Manufacturing Method, Heat Sink Furnished with Solder Film, and Semiconductor-Device-and-Heat-Sink Junction	
Application Number :		
Date :		
First Named Applicant:	Mr. Katsuhiro Itakura	
Confirmation Number:		
Attorney Docket Number:	39,036	
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Submitted By:		Elec. Sign.
James Judge Registered Number: 42,701		jjUDGE
		Sign. Capacity
		Agent

Documents being submitted:	Files
us-assignment	SM036-usassn.xml us-assignment.xsl us-assignment.dtd assgn.tif
us-request	SM036-usrequ.xml us-request.dtd us-request.xsl
us-fee-sheet	SM036-usfees.xml us-fee-sheet.xsl us-fee-sheet.dtd
application-body	SM036-trans.xml us-application-body.xsl application-body.dtd wipo.ent mathml2.dtd mathml2-qname-1.mod isoamsa.ent isoamsb.ent isoamsc.ent isoamsn.ent isoamso.ent isoamsr.ent isogr3.ent isomfrk.ent isomopf.ent isomscr.ent isotech.ent isobox.ent isocyr1.ent isocyr2.ent isodia.ent isolat1.ent isolat2.ent isonum.ent isopub.ent mmlextra.ent mmlalias.ent soextblx.dtd
us-declaration	dclr01.tif
us-declaration	dclr02.tif
us-declaration	dclr03.tif
Comments	